

The FMI Lead-free & Restriction of Hazardous Substances (RoHS) Program Overview

The FMI Lead-free program is in accordance with European Union (EU) Legislation: Restrictions on Hazardous Substances (RoHS) banning Pb after July 1, 2006. This lead free definition is per J-STD-006 (JEDEC/IPC): 0.1w percent. This definition applies to all of our components and assemblies, both through-hole and surface mount devices; metal and non-metal packages.

All FMI products are Lead Free and RoHS compliant (*unless specifically otherwise stated*);

not containing any of the following restricted substances:

Lead-	0.1% by weight
Cadmium-	0.01% by weight
Hexavalent Chromium-	0.1% by weight
Mercury-	0.1% by weight
Polybrominated Biphenyl (PBB)-	0.1% by weight
Polybrominated Diphenyl (PBDE)-	0.1% by weight
Bromodiphenyl Ether (BDE)-	0.1% by weight

External packaging and terminations are lead-free. The parts ability to withstand lead-free 260°C solder reflow profile internal PCB, components, solders, and terminations are all lead-free and RoHS compliant.

Marking and labeling of our packages and reels of lead-free components and assemblies are marked with a Pb-free symbol thereby indicating their status on all shipments as of 1 July 2005. Future upgraded marking requirements will be in accordance with JEDEC and IPC requirements.

An FMI Lead-free / RoHS Compliance Certificate will be issued with each shipment upon request. All updates to this policy will be posted on the FMI website.